

INFORMATION DISCLOSURE CITATION (Use several sheets if necessary)	Docket Number (Optional) TWI-12810	Application Number NEW
	Applicant(s) Allan Rosencwaig	
	Filing Date HEREWITH	Group Art Unit UNKNOWN

11050 U.S. PTO
 09/939817
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U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE
XZ	A	4,999,014	03/12/1991	Gold et al	356	382	05/04/1989
	B	5,042,951	08/27/1991	Gold et al	356	369	09/19/1989
	C	5,131,752	07/21/1992	Yu et al	356	369	06/28/1990
	D	5,620,556	04/15/1997	Henck	438	8	02/08/1995
	E	5,900,939	05/04/1999	Aspnes et al	356	369	06/17/1998
	F	6,085,002	07/04/2000	Qiu et al	385	52	03/16/1998

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO

OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

XZ	G	G.M.W. Kroesen et al., "Nonintrusive wafer temperature measurement using <i>in situ</i> ellipsometry," <i>J. Appl. Phys.</i> , Vol. 69, No. 5, 1 March 1991, pp. 3390 - 3392.
	H	C.T. Yu et al., "Using In Situ Ellipsometry for Film Thickness Endpoint Control," <i>Semiconductor International</i> , May 1991, pp. 166 - 169.
	I	M. Haverlag et al., "Ellipsometric study of silicon surface damage in electron cyclotron resonance plasma etching using CF ₄ and SF ₆ ," <i>Appl. Phys. Lett.</i> , Vol. 16, No. 24, 14 December 1992, pp. 2875 - 2877.
	J	M. Haverlag et al., "In situ ellipsometry and reflectometry during etching of patterned surfaces: Experiments and simulations," <i>J. Vac. Sci. Technol. B</i> , Vol. 10, No. 6, Nov/Dec 1992, pp. 2412 - 2418.
	K	N. Blayo et al., "Ultraviolet-visible ellipsometry for process control during the etching of submicrometer features," <i>J. Opt. Soc. Am. A</i> , Vol. 12, No. 3, March 1995, pp. 591 - 599.
	L	N. Blayo et al., "New Applications of Ellipsometry for Materials Characterization and VLSI Device Process Control," <i>The Electrochemical Society Proceedings</i> , Vol. 94-33, pp. 207 - 216.
	M	S.A. Henck, "In situ real-time ellipsometry for film thickness measurement and control," <i>J. Vac. Sci. Technol. A</i> , Vol. 10, No. 4, Jul/Aug 1992, pp. 934-938.
	N	R. W. Collins, "Automatic rotating element ellipsometers: Calibration, operation, and real-time applications," <i>Rev. Sci. Instrum.</i> , Vol. 61, No. 8, August 1990, pp. 2029 - 2062.
XZ	O	Copy of U.S. Patent Application No. 09/575,295, filed May 29, 2000, by inventors Lanhua Wei et al., entitled "Monitoring Temperature and Sample Characteristics Using a Rotating Compensator Ellipsometer." 17 pages of application, and 3 pages of informal drawings.

Examiner: XZ	Date Considered 8-18-02
Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	